

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L8	3616	(bond\$5 with (post pin pillar) with pad) with (chip wafer substrate die ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 05:08
L9	293	L8 and (waveguide fiber fibre light\$2guide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 05:15
L10	33	L8 and "385"/\$.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 05:15

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	((wafer die) and optic\$3 and electronic\$4 and pillar and pad and bond\$5 and (heat\$4 thermal\$5)).clm.	US-PGPUB	OR	ON	2006/09/05 04:39
L2	1	((wafer die) and optic\$3 and pillar and pad and bond\$5 and (heat\$4 thermal\$5)).clm.	US-PGPUB	OR	ON	2006/09/05 04:39
L3	14	((wafer die) and optic\$3 and electronic\$4 and pad and bond\$5 and (heat\$4 thermal\$5)).clm.	US-PGPUB	OR	ON	2006/09/05 04:46
L4	3	(substrate and optic\$3 and electronic\$4 and pad and waveguide and pillar).clm.	US-PGPUB	OR	ON	2006/09/05 04:50
L5	4	(substrate and optic\$3 and electronic\$5 and waveguide and pillar).clm.	US-PGPUB	OR	ON	2006/09/05 04:47
L6	4	(substrate and optic\$3 and electronic\$4 and pad and pillar).clm.	US-PGPUB	OR	ON	2006/09/05 04:51
L7	13	(substrate and optic\$3 and bond\$4 and pillar).clm.	US-PGPUB	OR	ON	2006/09/05 04:52